

SPECIFICATION FOR APPROVAL

CUSTOMER	_____
CUST. PART NO.	_____
CUST. DOC. REV.	_____
DESCRIPTION	POWER CHOKE(RoHS+H.F.)
SAMPLE LOT NO.	_____
PART NO.	CSMS0514D-XXXX-LRH
DOC. REV.	_____
DATE	_____

Once you approve this part, please sign and return this page to the following marked location.

Customer Signature: _____ Date: _____

This part currently development section. Production line can produce this series of products.

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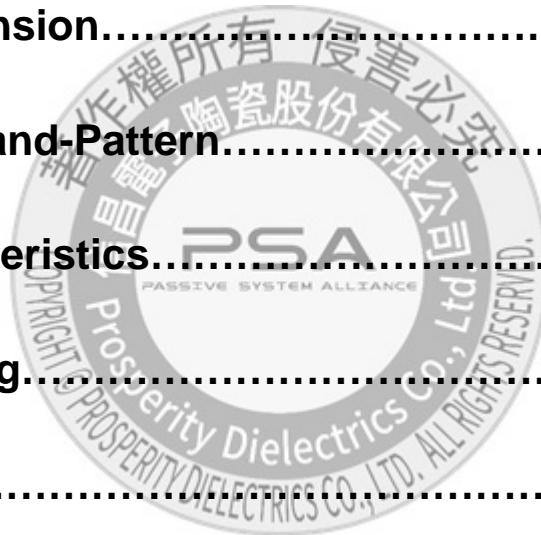
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TESTED BY	CHECKED BY	APPROVED BY

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SPECIFICATION FOR APPROVAL

CUSTOMER	CUSTOMER P/N	REV.	SPL. LOT NO.	
PART NAME POWER CHOKE (ROHS+H.F.)	PART NO. CSMS0514D-XXXX-LRH	REV.	DATE OF ISSUE	Q'TY 0 PCS

ENGINEERING CHANGE NOTICE - RECORD

REVISION NO.	REVISION DESCRIPTION	AUTHOR	DATE	REMARK



SPECIFICATION FOR APPROVAL

※This is a RoHS and REACH compliant product whose related documents are available on request.

※Graphic is only for dimensionally application.

1. Range of application:

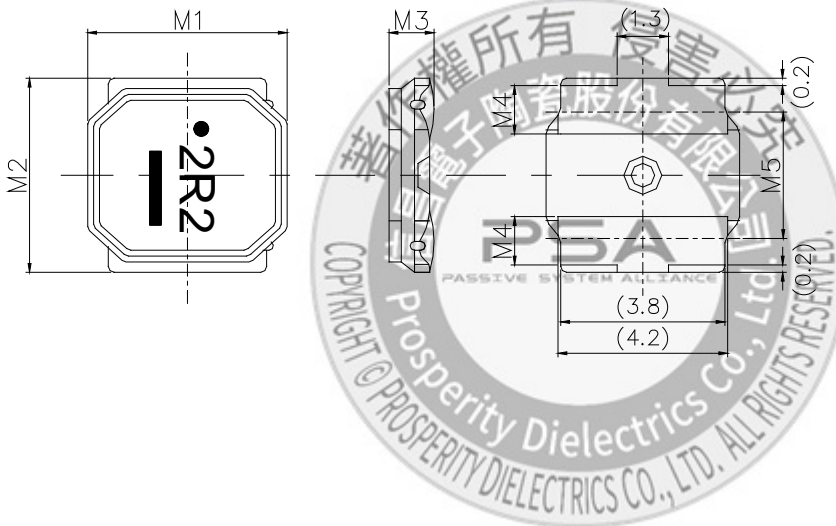
This specifications are applied to SMD Power Inductor, CSMS0514D.

2. Ordering code:

Example: **CSMS** **0514** **D** - **XXX** **X** - □□□
 (1) (2) (3) (4) (5) (6)

- (1) Product Type
- (2) External dimensions
- (3) Terminal Type
- (4) Inductance
- (5) Inductance tolerance
- (6) ROHS+HF

3. Mechanical Dimension:

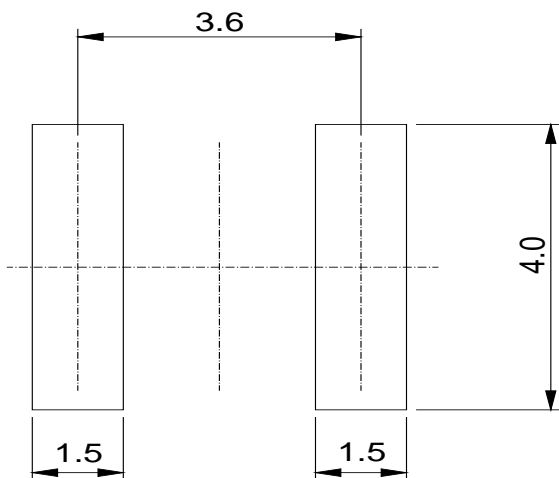


UNIT : mm

	DIM.	TOL.
M1	4.9	±0.2
M2	4.9	±0.2
M3	1.4	MAX.
M4	1.2	±0.2
M5	3.3	±0.2

(): Reference value

4. Recommended Land-Pattern:



(Unit: mm)

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5. Electrical Characteristics:

Part number	Nominal Inductance (uH)	Inductance Tolerance	DC Resistance (Ω) ±20%	Rated Current (mA)		Self-resonant Frequency (MHz) Min
				Saturation Current Idc1	Temperature Rise Current Idc2	
CSMS0514D-R47N-LRH	0.47	±30%	0.025	5800	3300	185
CSMS0514D-1R2N-LRH	1.2	±30%	0.045	3800	2400	86
CSMS0514D-2R2N-LRH	2.2	±30%	0.065	2800	2000	56
CSMS0514D-3R3N-LRH	3.3	±30%	0.080	2350	1700	48
CSMS0514D-4R7N-LRH	4.7	±30%	0.100	2050	1400	41
CSMS0514D-6R8M-LRH	6.8	±20%	0.150	1600	1200	33
CSMS0514D-100M-LRH	10	±20%	0.200	1400	1050	27
CSMS0514D-150M-LRH	15	±20%	0.320	1100	650	20
CSMS0514D-220M-LRH	22	±20%	0.450	900	550	16

1. Test Frequency: 100KHz, 1V.

2. Test Equipment:

Inductance: Chroma3302+1320 or equivalent.

DCR: Chroma16502 or equivalent.

SRF: HP4291B or equivalent.

3. Saturation Current Idc1: The value of current causes a 30% inductance reduction from initial value.

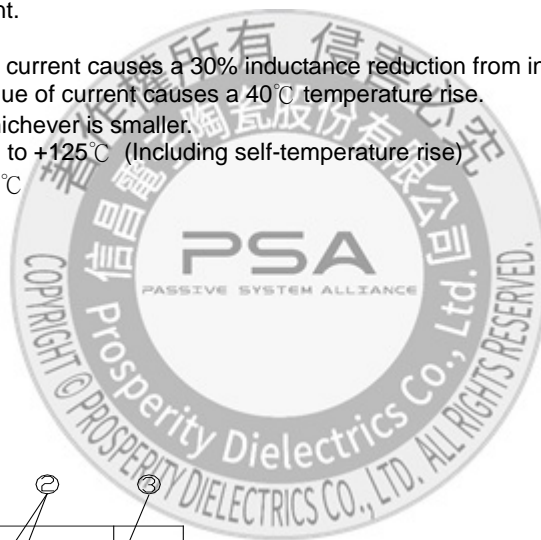
4. Temperature rise current Idc2: The value of current causes a 40°C temperature rise.

5. Rated Current: Either Idc1 or Idc2 whichever is smaller.

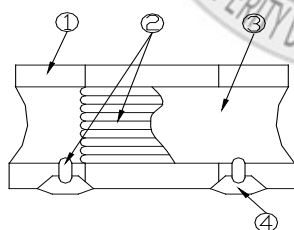
6. Operating Temperature Range: -25°C to +125°C (Including self-temperature rise)

7. Storage Temp. Range : -40°C to +85°C

8. MSL : Level 1



6. Structural Drawing:



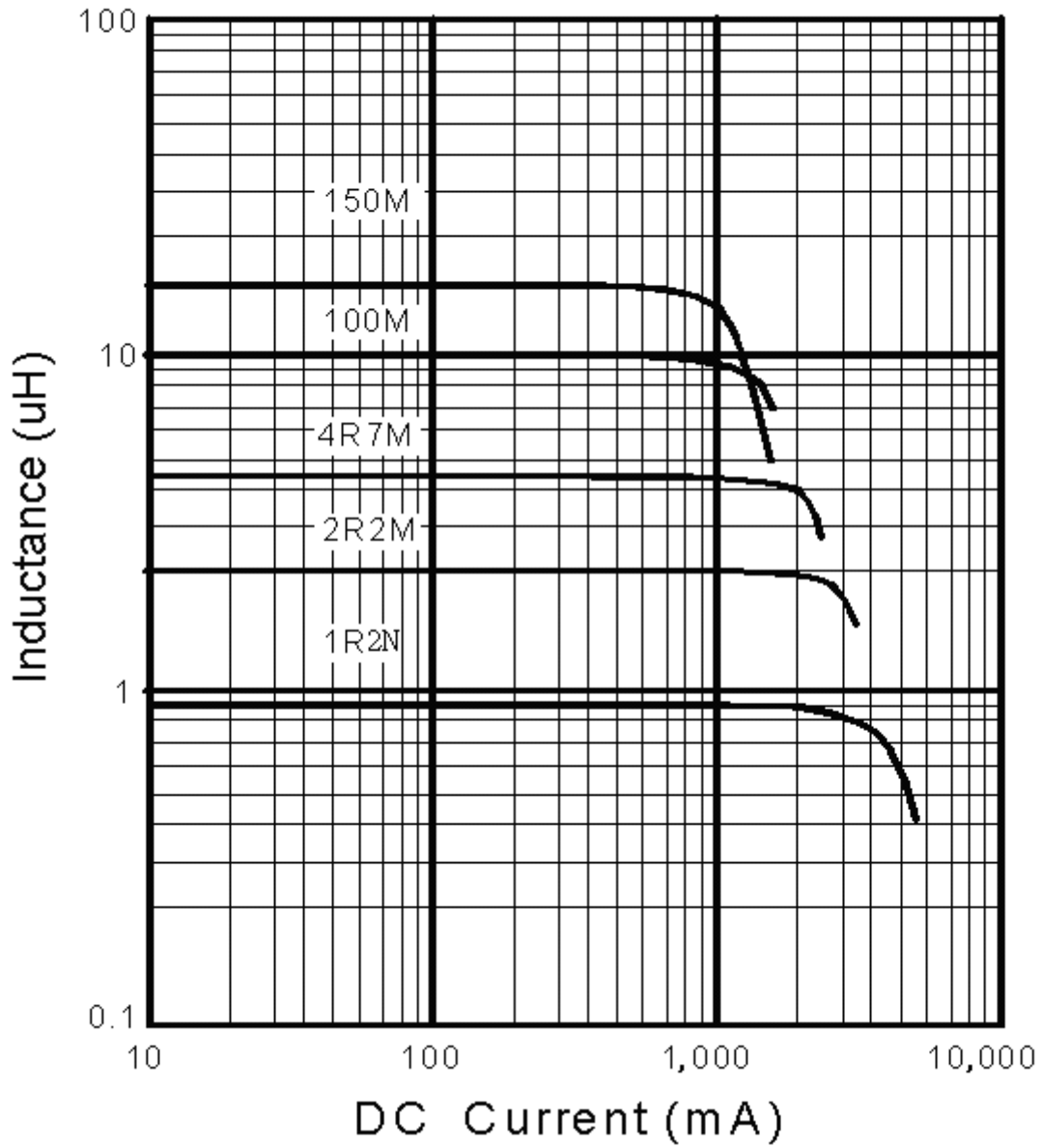
(Magnetic Shielded Type)

- | | | |
|-----------------------|---|----------|
| ① Ferrite core. | Ni-Zn ferrite | |
| ② Winding wire | Polyurethane-copper wire | |
| ③ Over-coating resin. | Epoxy resin, containing ferrite powder | |
| ④ Electrode | External electrode (substrate) | Ag |
| | External electrode (base plating) | Ni-Sn |
| | External electrode (top surface solder coating) | Sn-Ag-Cu |

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7. Electrical Curve :

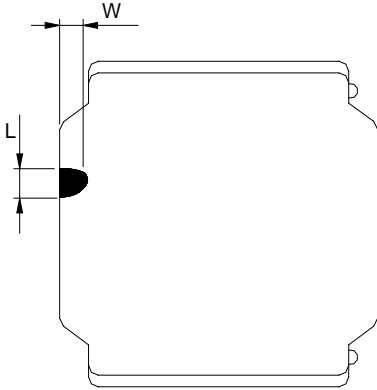
Inductance vs. DC Current



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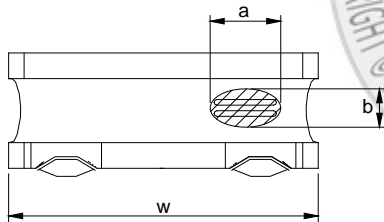
8. Core Chipping:

The appearance standard of the chipping size in top side, of bottom side ferrite Core is following dimension



L	W
1.5mmMax.	1.5mmMax.

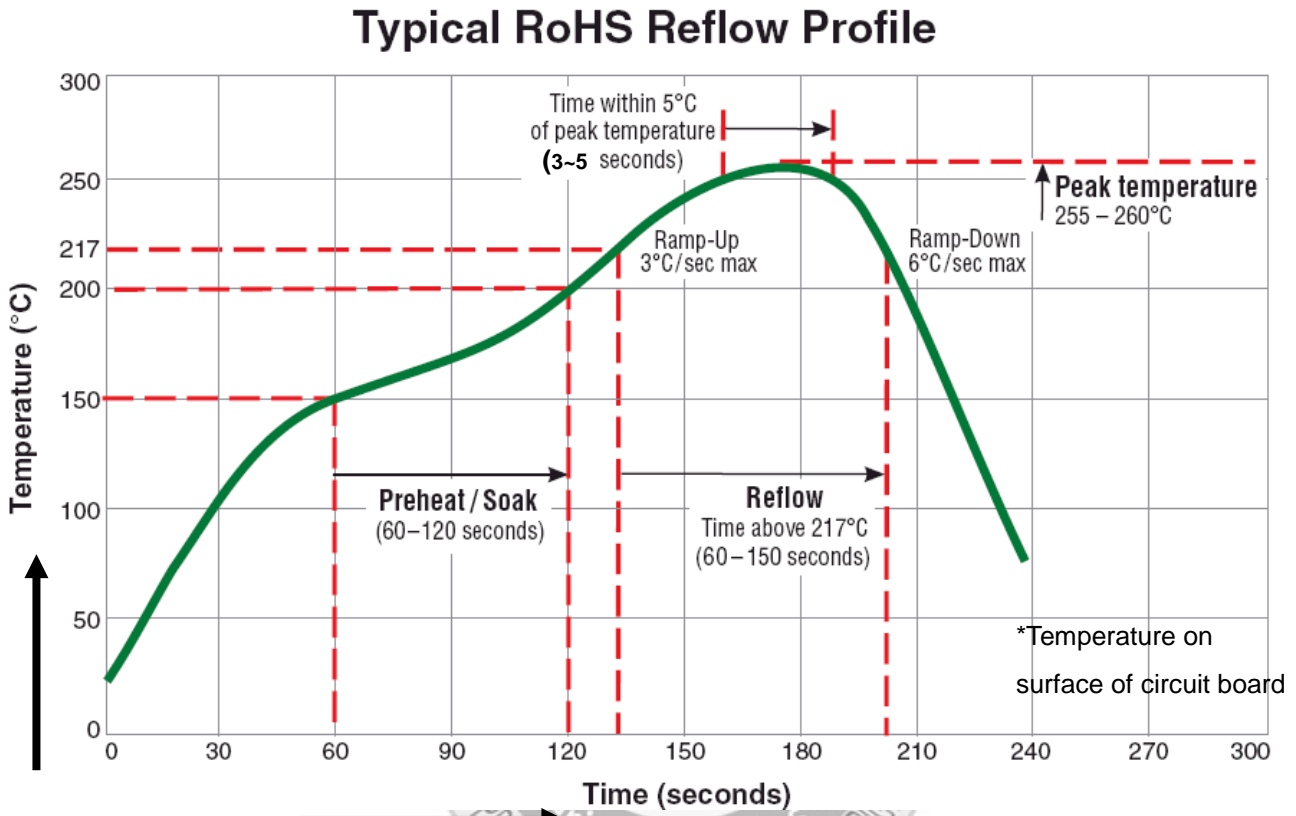
9. Exposed wire tolerance limit of coating resin part on product side Size of exposed wire occurring to coating resin is specified below.



- ① Width direction (dimension a): Acceptable when $a \leq w/2$
Nonconforming when $a > w/2$
- ② Length direction (dimension b): Dimension b is not specified.
- ③ When total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, that is acceptable.

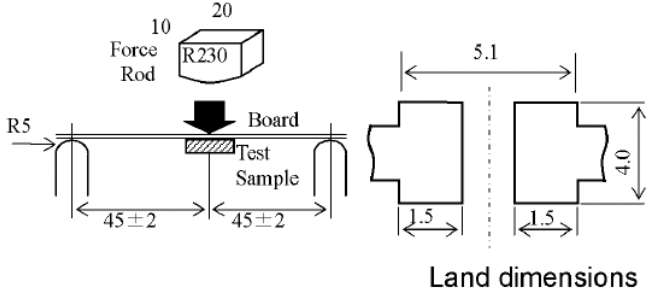

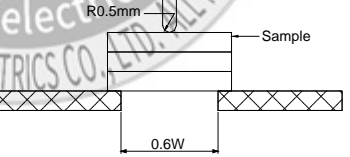
SPECIFICATION FOR APPROVAL

10. Reflow Profile Chart (Reference):



SPECIFICATION FOR APPROVAL

11. Reliability & Test Conditions

	Test Item	Standard	Test method
MECHANICAL CHARACTERISTICS	Resistance to Deflection	No damage .	<p>The test samples shall be soldered to the test board by the reflow soldering conditions show in Reflow Profile Chart As illustrated below, apply force in the direction of the Arrow indicating until deflection of the test board Reaches to 2 mm.</p>  <p style="text-align: right;">Land dimensions</p> <p>Test board size :100×40×10 Test board material I: glass epoxy-resin Solder cream thickness:0.15</p> <p style="text-align: right;">Unit: mm</p>
	Adhesion of Terminal Electrode	Shall not come off PC board	<p>The test samples shall be soldered to the test board By the reflow soldering conditions shown in Reflow Profile Chart</p>  <p>Applied force:10 N to X and Y directions Duration:5 s. Solder cream thickness:0.15 mm (Refer to recommended Land Pattern Dimensions Defined in "Precaution")</p>
	Body strength	No damage	<p>Applied force :30 N Duration :10 s</p> 

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	Test Item	Standard	Test method															
	Resistance to Vibration	$\Delta L/L$:within $\pm 10\%$ No abnormality observed In appearance	The test samples shall be soldered to the test board by The reflow soldering conditions shown in Reflow Profile Chart.Then It shall be submitted to below test conditions <table border="1" style="width: 100%; margin-top: 5px;"> <tr> <td>Frequency range</td> <td>10Hz~55Hz</td> </tr> <tr> <td>Total Amplitude</td> <td>1.5mm(May not exceed acceleration 196 m/S²)</td> </tr> <tr> <td>Sweeping Method</td> <td>10Hz to 55Hz to 10 Hz for 1 min.</td> </tr> <tr> <td>Time</td> <td>For 2 hours on each X,Y, and Z axis.</td> </tr> </table>	Frequency range	10Hz~55Hz	Total Amplitude	1.5mm(May not exceed acceleration 196 m/S ²)	Sweeping Method	10Hz to 55Hz to 10 Hz for 1 min.	Time	For 2 hours on each X,Y, and Z axis.							
Frequency range	10Hz~55Hz																	
Total Amplitude	1.5mm(May not exceed acceleration 196 m/S ²)																	
Sweeping Method	10Hz to 55Hz to 10 Hz for 1 min.																	
Time	For 2 hours on each X,Y, and Z axis.																	
	Resistance to Soldering heat (Reflow)	$\Delta L/L$:within $\pm 10\%$ No abnormality observed In appearance	The test sample shall be exposed to reflow oven at 230 ± 5 deg C for 40 seconds, with peak temperature at 260 ± 5 deg C for 5 seconds, 2 times. Test board thickness:1.0 mm Test board material :glass epoxy-resin															
	Solder ability	At least 90% of surface of terminal electrode is covered by new solder.	The test samples shall be dipped in flux, and then Immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25% <table border="1" style="width: 100%; margin-top: 5px;"> <tr> <td>Solder Temperature</td> <td>245\pmdeg C</td> </tr> <tr> <td>Time</td> <td>5\pm1.0 S.</td> </tr> <tr> <td>Immersing Speed</td> <td>25 mm/s</td> </tr> </table>	Solder Temperature	245 \pm deg C	Time	5 \pm 1.0 S.	Immersing Speed	25 mm/s									
Solder Temperature	245 \pm deg C																	
Time	5 \pm 1.0 S.																	
Immersing Speed	25 mm/s																	
	Temperature Characteristics	$\Delta L/L$:within $\pm 20\%$ No abnormality observed In appearance	Measurement of inductance shall be taken at temperature Range within -25 deg C to +85 deg C. With reference to inductance value at +20 deg C, change Rate shall be calculated.															
	Thermal shock	$\Delta L/L$:within $\pm 10\%$ No abnormality observed In appearance	The test samples shall be soldered to test board By the reflow soldering conditions shown in Reflow Profile Chart The test samples shall be placed at specified temperature for specified time by step 1 to 4 as shown in below table in sequence. Shown in below table in sequence. The temperature cycle shall be repeated 100 cycles. Conditions of steps for 1 cycle <table border="1" style="width: 100%; margin-top: 5px;"> <thead> <tr> <th>Step</th> <th>Temperature</th> <th>Time(min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-40± 3 deg C</td> <td>30± 3</td> </tr> <tr> <td>2</td> <td>Room Temp</td> <td>3 maximum</td> </tr> <tr> <td>3</td> <td>85± 2 deg C</td> <td>30± 3</td> </tr> <tr> <td>4</td> <td>Room Temp</td> <td>3 maximum</td> </tr> </tbody> </table>	Step	Temperature	Time(min)	1	-40 ± 3 deg C	30 ± 3	2	Room Temp	3 maximum	3	85 ± 2 deg C	30 ± 3	4	Room Temp	3 maximum
Step	Temperature	Time(min)																
1	-40 ± 3 deg C	30 ± 3																
2	Room Temp	3 maximum																
3	85 ± 2 deg C	30 ± 3																
4	Room Temp	3 maximum																
	Low Temperature life Test	$\Delta L/L$:within $\pm 10\%$ No abnormality observed In appearance	The test samples shall be soldered to the test board by The reflow soldering conditions shown in Reflow Profile Char. After that, the test samples shall be placed at test Conditions as shown in below table. <table border="1" style="width: 100%; margin-top: 5px;"> <tr> <td>Temperature</td> <td>-40± 2 deg C</td> </tr> <tr> <td>Time</td> <td>500 +24/-0 h</td> </tr> </table>	Temperature	-40 ± 2 deg C	Time	500 +24/-0 h											
Temperature	-40 ± 2 deg C																	
Time	500 +24/-0 h																	

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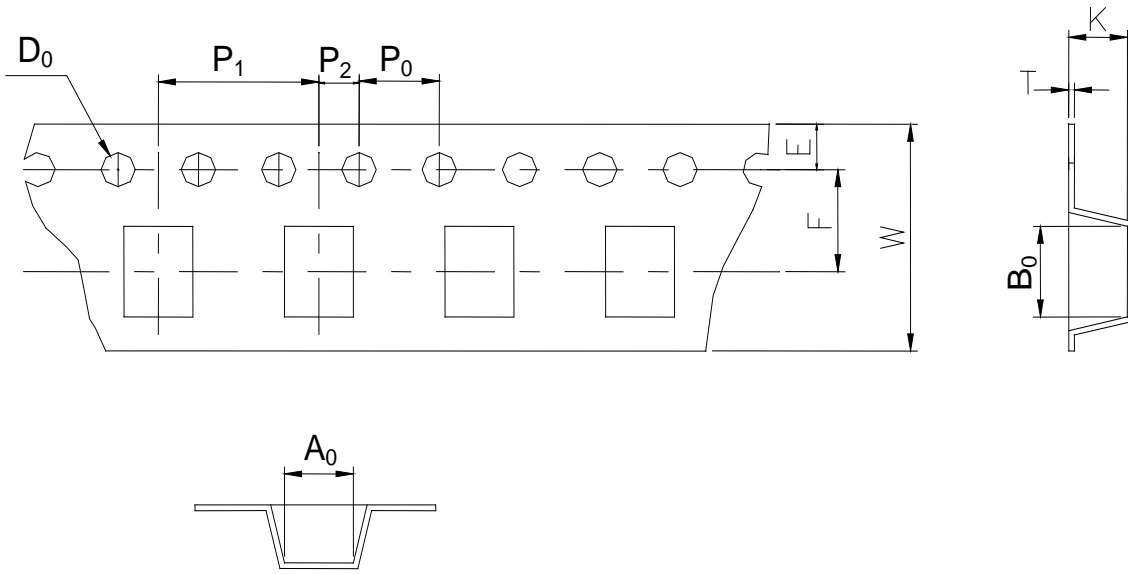
	Test Item	Standard	Test method							
ENVIRONMENT TESTS	Loading at high temperature life test	Δ L/L: within $\pm 10\%$ No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Reflow Profile Chart. The test samples shall be placed in thermostatic oven set at specified temperature and applied the rated current continuously as shown in below table. <table border="1" style="margin-left: auto; margin-right: auto; border-collapse: collapse;"> <tr> <td style="text-align: center;">Temperature</td> <td style="text-align: center;">85\pm2 deg C</td> </tr> <tr> <td style="text-align: center;">Applied current</td> <td style="text-align: center;">Rated current (Refer to Page 2)</td> </tr> <tr> <td style="text-align: center;">Time</td> <td style="text-align: center;">500+24/-0 h</td> </tr> </table>	Temperature	85 \pm 2 deg C	Applied current	Rated current (Refer to Page 2)	Time	500+24/-0 h	
	Temperature	85 \pm 2 deg C								
	Applied current	Rated current (Refer to Page 2)								
Time	500+24/-0 h									
Damp heat life test	Δ L/L: within $\pm 10\%$ No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Reflow Profile Chart. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table. <table border="1" style="margin-left: auto; margin-right: auto; border-collapse: collapse;"> <tr> <td style="text-align: center;">Temperature</td> <td style="text-align: center;">60\pm2 deg C</td> </tr> <tr> <td style="text-align: center;">Humidity</td> <td style="text-align: center;">90~95%RH</td> </tr> <tr> <td style="text-align: center;">Time</td> <td style="text-align: center;">500+24/-0 h</td> </tr> </table>	Temperature	60 \pm 2 deg C	Humidity	90~95%RH	Time	500+24/-0 h		
Temperature	60 \pm 2 deg C									
Humidity	90~95%RH									
Time	500+24/-0 h									
Loading under Damp heat life test	Δ L/L: within $\pm 10\%$ No abnormality observed in appearance.	The test samples shall be soldered to the test board by the reflow soldering conditions shown in Reflow Profile Chart. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table. <table border="1" style="margin-left: auto; margin-right: auto; border-collapse: collapse;"> <tr> <td style="text-align: center;">Temperature</td> <td style="text-align: center;">60\pm2 deg C</td> </tr> <tr> <td style="text-align: center;">Humidity</td> <td style="text-align: center;">90~95%RH</td> </tr> <tr> <td style="text-align: center;">Applied current</td> <td style="text-align: center;">Rated current (Refer to Page3))</td> </tr> <tr> <td style="text-align: center;">Time</td> <td style="text-align: center;">500+24/-0 h</td> </tr> </table>	Temperature	60 \pm 2 deg C	Humidity	90~95%RH	Applied current	Rated current (Refer to Page3))	Time	500+24/-0 h
Temperature	60 \pm 2 deg C									
Humidity	90~95%RH									
Applied current	Rated current (Refer to Page3))									
Time	500+24/-0 h									

Standard measuring condition	Unless otherwise specified, the test samples are placed at room temperature and humidity and measured with 48 hours after exposure to test conditions
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SPECIFICATION FOR APPROVAL

12. Tape & Reel Packaging Dimensions: 12-1 Dimensions

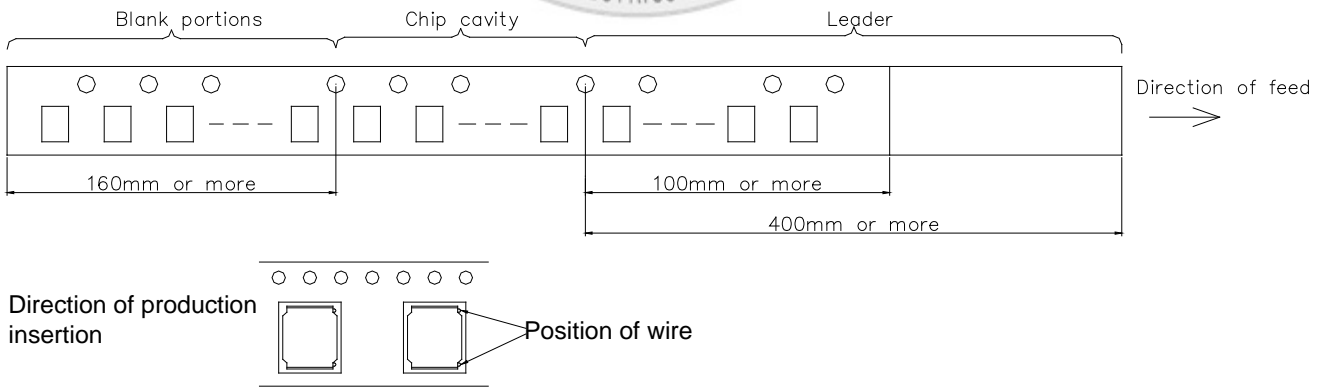
Unit: mm



A_0	B_0	W	F	E	P_1	P_2	P_0	D_0	T	K
5.25 ± 0.1	5.25 ± 0.1	12.0 ± 0.3	5.5 ± 0.1	1.75 ± 0.1	8.0 ± 0.1	2.0 ± 0.1	4.0 ± 0.1	$\Phi 1.5$ $+0.1$ -0	0.3 ± 0.1	1.4 ± 0.1

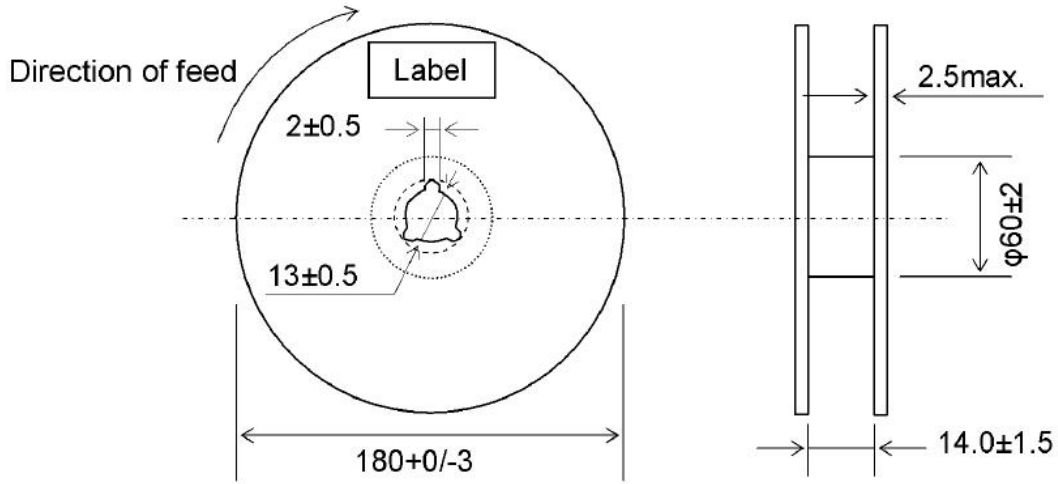


12-2 Direction of rolling



SPECIFICATION FOR APPROVAL

12-3 Reel



Label position: On the opposite side of sprocket holes side of reel

12-4 Top tape strength



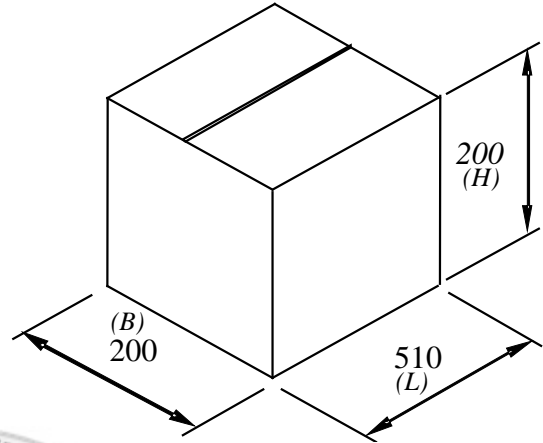
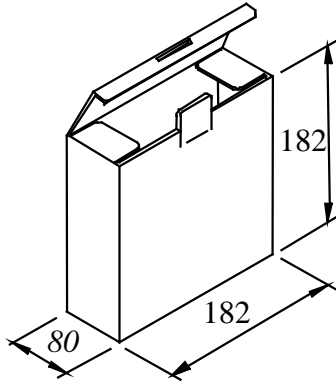
Peel-off strength: 0.1N~1.3N

Peel-off angle: $165^\circ \sim 180^\circ$

Peel-off speed: 300mm/min

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12-5 Dimensions of packing box (for Tape & Reel package)



Reel	4Reel/box	6box/carton
Q'ty (pcs)	Q'ty (pcs)	Q'ty (pcs)
1000	4000	24000

